

Data sheet of HY910

Introduction / 產品簡介

HY910 thermal glue

Thermal conductive filler is a milky paste <alcohol type>, the product is thermal conductivity and insulation properties are excellent grease mixed with an organic filler, this silicone with high thermal conductivity, low scores discharge and high temperature stability, after exposure to air rapid solidification, odorless and tasteless, no corrosion of the substrate and so on. Insulation helps to establish an absolute thermal environment that accelerates electronic, electrical devices heat conduction velocity, thereby improving cooling efficiency.

HY910 has good thermal conductivity. Widely used in electrical and electronic cooling, power, transistors and thermistor thermal adhesive sealing, PTC bonding insulation. Especially suitable for high performance requirements for thermal adhesive seal. Single component, neutral cure, with [trace water molecules in the air cause crosslinking condensation reaction from the table and gradually vulcanized into high performance elastomer. After curing has excellent flame retardant properties, aging resistance, high temperature (-60 ~ +250 °C), insulation, moisture, no swelling, for most metal and nonmetal has good adhesion, capable of a variety of electronic components for sealing, bonding, solvent-free, it will not emit toxic gases, does not pollute the surrounding environment. Line with the EU ROHS directive.

Features / 特性

- Appearance / 產品外觀: White
- Melting capacity (@200°C environment for 24 hours): 0%
- Evaporation (@200°C environment for 24 hours): 0.001%
- Infer (@25°C): >2.3
- 熱傳導系數: > 0.671 W/m-k
- 熱阻抗: < 0.246 c-in/W
- 抗弧強度: 120 seconds
- 表干時間 (@25°C): 3 min.
- 黏接強度 (Mpa): 1.8
- 絕緣系數 (100Hz/kvac): 5.1
- 絕緣系數 (1000Hz/kvac): 5.0

◆產品壽命 / Shelf Life

Storage time is one year before the closure, after opening the storage time of six months.

◆儲存條件 / Shortage condition

Finished vacuum packaging, the temperature is maintained at temperature 15~20 °C, Proof and waterproof, temperature set at -45~+180 °C, six months after opening

Shelf life is kept constant at 0~15 °C. If exposed to other circumstances, cause the cure.

Open the vacuum packaging, refrigeration temperature was maintained at 0~15 °C

Main compositions

- 有機硅材料 /Silicone Material : 30%
- 導熱材料 /Thermal Conductive Material : 40%
- 補強劑 /Strengthen Fillers : 20%
- 交聯劑 /Crossing Agent : 10%

Packaging / 產品包裝

鋁管支裝 + 真空包裝



Using methods and precautions

1 . clean and dry surface of the object, hand squeeze the hose or install special plastic extrusion equipment can be extruded.

2 . sizing thickness not exceeding 0,5 mm. Sizing fully dry after 12 hours, after 24 hours the highest strength, do not fully cured prior to the force.

3 . smear, let 10s after exposure, allowed to reach optimum viscosity, the other with an adhesive bonding surface before bonding together to achieve the best results.

4 . sizing process is not a one-time run out, pay attention to sealing a plastic mouth; sizing to avoid contact with the eyes; construction and curing process can not be closed, should be kept well ventilated environment.

HY910系列 导热界面材料

专为电子零部件降温设计的导热界面材料

★HY910导热胶是一种乳白膏状导热填料<单组份，温室导热硅胶>

性能:

本产品是用导热性能和绝缘性能均极好的填料与有机硅脂混合而成的,这种硅胶具备高热导性,低分泄和耐高温稳定性,在空气中暴露后能迅速凝固,且无味、无臭、对基材不腐蚀等优点.有助于建立一个绝对的绝缘散热环境,能够加快电子、电气装置的热传导速度,从而提高散热效率.

特性

比重:[25°C(77° F)]	_____	>2.3
热传导系数:W/m-k	_____	>0.671
热阻抗:c-in/W	_____	<0.246
抗弧强度:seconds	_____	120
表干时间[25°C]	_____	3 min
黏接强度:	_____	1.8Mpa
绝缘系数: 100Hz/Kvac	_____	5.1
1000Hz/Kvac	_____	5.0

成份

有机硅材料 /Silicone Material	-----	30%
导热材料 /Thermal Conductive Material	-----	40%
补强剂 /Stvengtahen Fillers	-----	20%
交联剂 /Crossing Agent	-----	10%

产品图片



※本产品耐温,不自燃,一般室温储存方式即可。

以上数据由深圳市华能智研电子有限公司实验室测试所得,该实验室保留最终解释权。

